

STB80NE03L-06

N-channel 30V - 0.005Ω - 85A - D²PAK STripFET™ Power MOSFET

General features

Туре	V _{DSS}	R _{DS(on)}	I _D
STB80NE03L-06	30V	<0.006Ω	80A

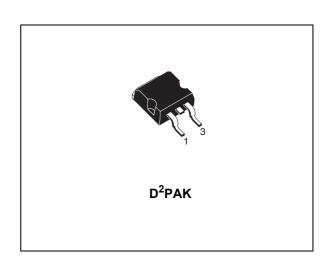
- Exceptional dv/dt capability
- Low gate charge 100°C
- 100% Avalanche tested

Description

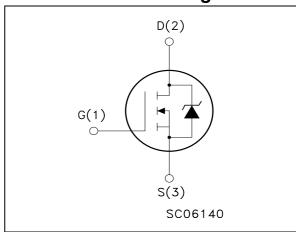
This Power MOSFET is the latest development of STMicroelectronics unique "Single Feature Size™" strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

Applications

■ Switching application



Internal schematic diagram



Order codes

Part number	Marking	Package	Packaging
STB80NE03L-06	B80NE03L	D ² PAK	Tape & reel

Contents STB80NE03L-06

Contents

1	Electrical ratings	3
2	Electrical characteristics	4
	2.1 Electrical characteristics (curves)	6
3	Test circuit	8
4	Package mechanical data	9
5	Packaging mechanical data1	1
6	Revision history	2

STB80NE03L-06 Electrical ratings

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source voltage (V _{GS} = 0)	30	V
V _{DGR}	Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)	30	V
V _{GS}	Gate-source voltage	± 20	V
I _D	Drain current (continuous) at T _C = 25°C	80	Α
I _D	Drain current (continuous) at T _C = 100°C	60	Α
I _{DM} ⁽¹⁾	Drain current (pulsed)	320	Α
	Derating factor	1	
P _{TOT}	Total dissipation at T _C = 25°C	150	W
dv/dt (2)	Peak diode recovery voltage slope	7	V/ns
T _J Tstg	Operating junction temperature Storage temperture	nperature -55 to 175	

^{1.} Pulse width limited by safe operating area

Table 2. Thermal resistance

Symbol	Parameter	Value	Unit
R _{thJC}	Thermal resistance junction-case Max	1	°C/W
R _{thJA}	Thermal resistance junction-ambient Max	62.5	°C/W
T _I	Maximum lead temperature for soldering purpose	300	°C

Table 3. Avalanche characteristics

Symbol	Parameter	Max Value	Unit
I _{AR}	Avalanche current, repetitive or not-repetitive (pulse width limited by Tj max)	80	Α
E _{AS}	Single pulse avalanche energy (starting Tj=25°C, Id=lar, Vdd=50V)	600	mJ

^{2.} $I_{SD} \leq$ 20A, di/dt \leq 100A/ μ s, V_{DD} = 80% $V_{(BR)DSS}$

Electrical characteristics STB80NE03L-06

2 Electrical characteristics

(T_{CASE} = 25°C unless otherwise specified)

Table 4. On/off states

Symbol	Parameter Test conditions		Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$ I_{\rm p} = 250 \text{uA} \text{ V}_{\rm pos} = 0$				V
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	V_{DS} = Max rating, V_{DS} = Max rating @125°C			1 10	μ Α μ Α
I _{GSS}	Gate body leakage current (V _{DS} = 0)	V _{DS} = ± 20V			±100	nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	1.7	2.5	V
R _{DS(on)}	Static drain-source on resistance	$V_{GS} = 10 \text{ V}, I_D = 40 \text{A}$ $V_{GS} = 4.5 \text{ V}, I_D = 40 \text{A}$		0.005	0.006 0.008	Ω Ω

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
9 _{fs} ⁽¹⁾	Forward transconductance	$V_{DS} > I_{D(on)} \times R_{DS(on)max},$ $I_D = 40A$	30	50		S
C _{iss} C _{oss} C _{rss}	Input capacitance Output capacitance Reverse Transfer Capacitance	$V_{DS} = 25V, f = 1 \text{ MHz},$ $V_{GS} = 0$		6500 1500 500		pF pF pF
Q _g Q _{gs} Q _{gd}	Total gate charge Gate-source charge Gate-drain charge	$V_{DD} = 24 \text{ V}, I_{D} = 80 \text{A},$ $V_{GS} = 5 \text{V}$		95 30 44	130	nC nC nC

^{1.} Pulsed: pulse duration = 300µs, duty cycle 1.5%

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time	V _{DD} = 15 V, I _D = 40 A		40	55	ns
t _r	Rise time	$R_G = 4.7\Omega V_{GS} = 4.5 V$ Figure 12.		260	350	ns
t _{r(Voff)}	Off-voltage rise time	$V_{DD} = 24 \text{ V}, I_D = 80 \text{ A},$		70	95	ns
t _f	Fall time	$R_G = 4.7\Omega$, $V_{GS} = 5V$		165	220	ns
t _c	Cross over time	Figure 12.		250	340	ns

Table 7. Source drain diode

Symbol	Parameter Test conditions		Min	Тур.	Max	Unit
I _{SD}	Source-drain current Source-drain current (pulsed)				80 320	A A
V _{SD} ⁽²⁾	Forward on voltage	$I_{SD} = 80A, V_{GS} = 0$			1.5	V
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 80 \text{ A},$ di/dt = 100A/ μ s, $V_{DD} = 15$ V, $T_{J} = 150^{\circ}\text{C}$ Figure 15.		75 0.14 4		ns nC A

^{1.} Pulse with limited by safe operating area

^{2.} Pulsed: pulse duration = $300\mu s$, duty cycle 1.5%

Electrical characteristics STB80NE03L-06

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

Figure 2. Thermal impedance

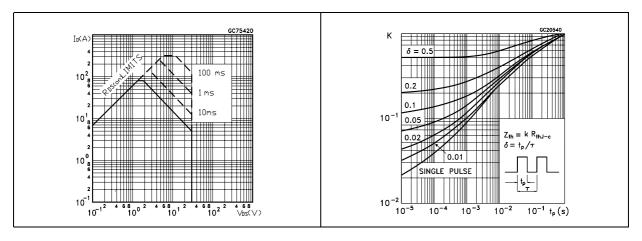


Figure 3. Output characterisics

Figure 4. Transfer characteristics

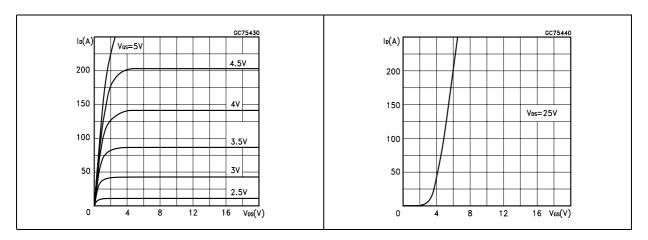
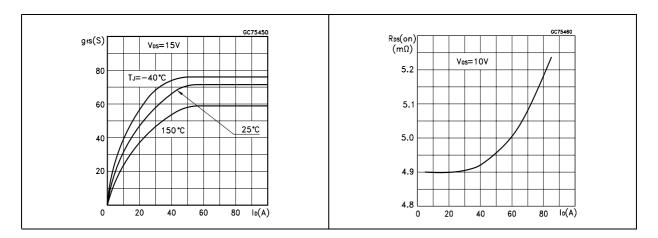


Figure 5. Transconductance

Figure 6. Static drain-source on resistance



6/13

Figure 7. Gate charge vs gate-source voltage Figure 8. Capacitance variations

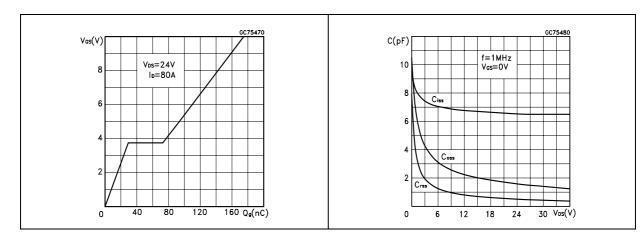


Figure 9. Normalized gate threshold voltage Figure 10. Normalized on resistance vs vs temperature temperature

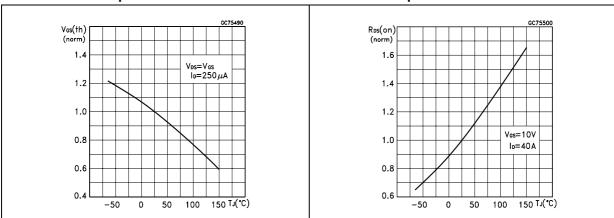
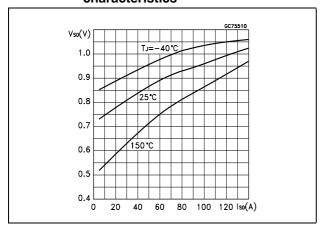


Figure 11. Source-drain diode forward characteristics



577

Test circuit STB80NE03L-06

3 Test circuit

Figure 12. Switching times test circuit for resistive load

Figure 13. Gate charge test circuit

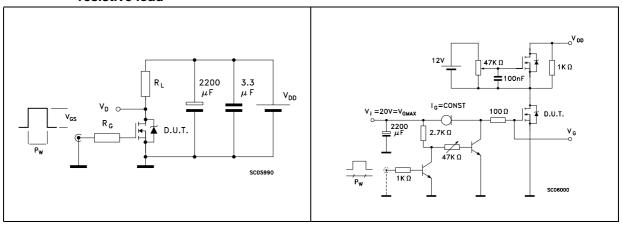


Figure 14. Test circuit for inductive load switching and diode recovery times

Figure 15. Unclamped inductive load test circuit

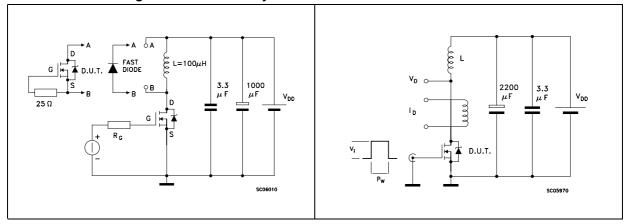
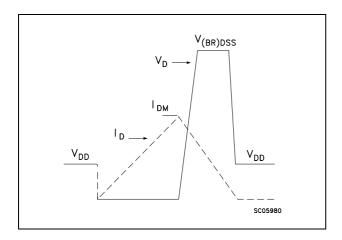


Figure 16. Unclamped inductive waveform



577

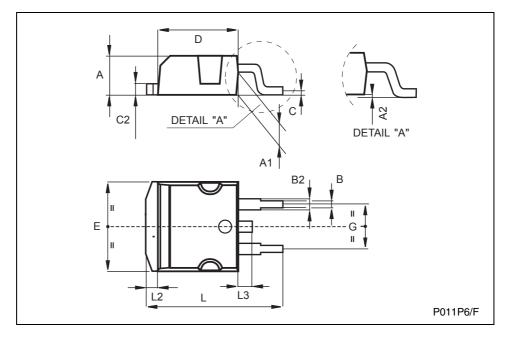
4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

9/13

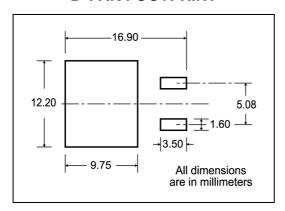
TO-263 (D²PAK) MECHANICAL DATA

DIM.		mm			inch	
DIW.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	4.4		4.6	0.173		0.181
A1	2.49		2.69	0.098		0.106
В	0.7		0.93	0.027		0.036
B2	1.14		1.7	0.044		0.067
С	0.45		0.6	0.017		0.023
C2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
E	10		10.4	0.393		0.409
G	4.88		5.28	0.192		0.208
L	15		15.85	0.590		0.624
L2	1.27		1.4	0.050		0.055
L3	1.4		1.75	0.055		0.068

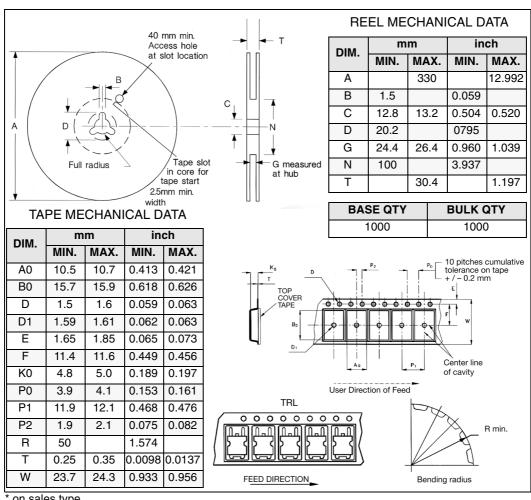


Packaging mechanical data 5

D²PAK FOOTPRINT



TAPE AND REEL SHIPMENT



on sales type

Revision history STB80NE03L-06

6 Revision history

Table 8. Revision history

Date	Revision	Changes	
21-Jun-2004	5	Preliminary version	
25-Jul-2006	6	New template, SOA updated	

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